

Sip Switches, Low Profile, Vertical and Right Angle

FEATURES:

- End-to-end stackable in .100" center (SSV/SLV) versions
- High pressure wiping contacts allows aqueous or solvent cleaning
- Gas tight contacts (280,000 PSI)
- Ceramic substrate allows wave soldering temperature of 245° for up to 10 seconds (SLV Version)
- 2 SIP switches take up less board space than 1 DIP switch

ENVIRONMENTAL SPECIFICATIONS:

Operating Temperature-30°C to +85°C
 Storage Temperature-45°C to +100°C
 Solder Heat ResistanceWave soldering temperatures of 245°C ± 5°C with switch in off position 30 seconds when mounting on a .060" thick PCB per MIL-STD 202, Method 210

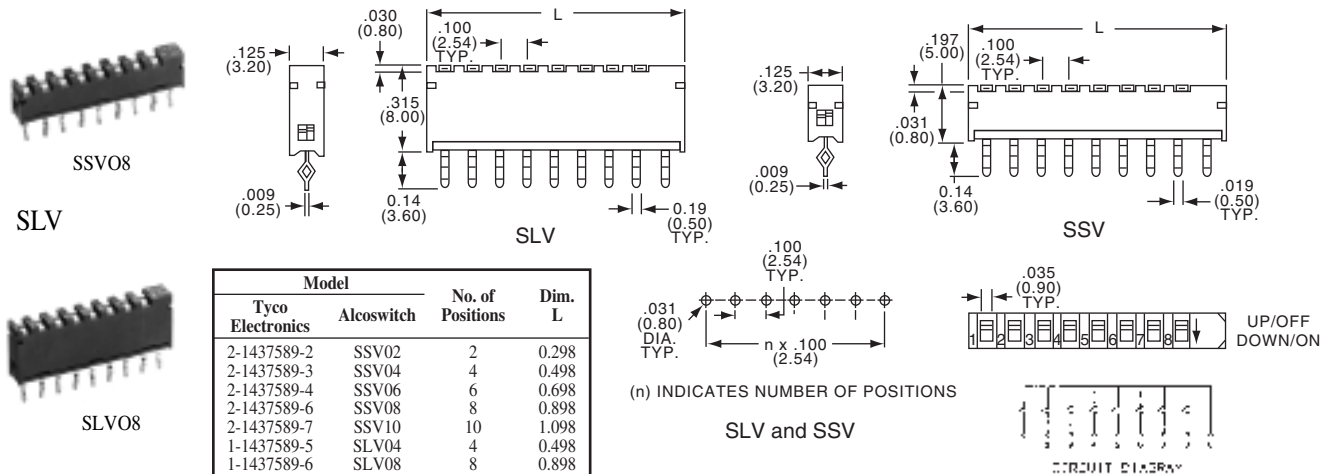
MATERIAL SPECIFICATIONS:

BasePPS 94V-0/Encapsulated Ceramic (SLV/SLH)
 CoverPBT 94V-0
 ContactsGold flashed Beryllium copper
 Actuator MaterialPolyamide
 Terminals/Fixed ContactsSolder coated copper alloy
 Terminal SealInsert molded
 Process SealGas tight contacts

TYPICAL PERFORMANCE CHARACTERISTICS:

Contact Rating0.4 VA @ 20 VDC max.
 Initial Contact Resistance50 Milliohms max.
 Insulation Resistance100 Megohms min. @ 100 VDC
 Dielectric Strength500 VAC
 Actuation Force800 Grams max.
 Actuator Travel50°
 Life Expectancy1,000 Cycles

SSV



SSH

